

Features

- Wide Bandwidth Fixed Attenuation up to 50 GHz
- 2, 3, 4, 6, 10, 15, and 20 dB Values
- Two 0 dB thru lines
- 50 Ω Impedance
- 27 dBm Power Handling
- Bare Die
- RoHS* Compliant

Applications

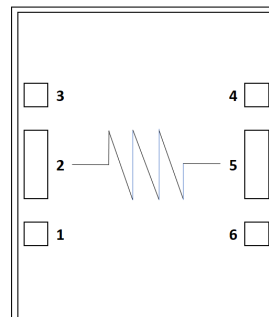
- Telecom Infrastructure
- Fiber Optics
- Sensors
- Test Instruments
- Microwave Radio
- General Purpose

Description

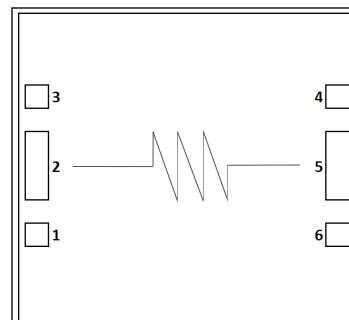
The MAAT-0110xx-DIE are broadband bidirectional, fixed attenuator values including 0, 2, 3, 4, 6, 10, 15, and 20 dB

The MAAT-0110xx-DIE are suited for many applications that require a small attenuator die for chip-and-wire assemblies delivering flat attenuation and excellent return loss.

Functional Schematic



MAAT-011022 / 024 / 025 / 026 / 027 / 028 / 029



MAAT-011023 / 030

Ordering Information¹

Part Number	Description
MAAT-011022-DIE	Thru Line
MAAT-011023-DIE	Thru Line
MAAT-011024-DIE	2 dB Attenuator
MAAT-011025-DIE	3 dB Attenuator
MAAT-011026-DIE	4 dB Attenuator
MAAT-011027-DIE	6 dB Attenuator
MAAT-011028-DIE	10 dB Attenuator
MAAT-011029-DIE	15 dB Attenuator
MAAT-011030-DIE	20 dB Attenuator

1. Die supplied in gel pack.

Pin Configuration^{2,3}

Pin #	Name	Function
1,3,4,6	GND	Ground
2	RF _{IN}	RF Input
5	RF _{OUT}	RF Output

2. The backside of the die must be connected to RF, DC and thermal ground.
3. Ground pins may be left open.

¹ * Restrictions on Hazardous Substances, compliant to current RoHS EU directive.

Electrical Specifications: (measured with 150 μ m G-S-G RF probes); $T_A = 25^\circ\text{C}$, $Z_0 = 50 \Omega$

Part Number	Attenuation 0.05 - 24 GHz 25 - 50 GHz			Return Loss In/Out 0.05 - 24 GHz 25 - 50 GHz	Input P1dB 0.05 - 30 GHz	Input IP3 0.05 - 30 GHz
	dB			dB	dBm	dBm
	Min.	Typ.	Max.	Typ.	Typ.	Typ.
MAAT-011022-DIE	—	0.1 0.2	0.15 0.25	21.0 17.5	—	—
MAAT-011023-DIE	—	0.2 0.3	0.3 0.4	21.0 17.5	—	—
MAAT-011024-DIE	1.7 1.6	1.9 2.0	2.1 2.4	21.0 17.5	27	40
MAAT-011025-DIE	2.8 2.75	3.0 3.1	3.2 3.5	21.0 17.5	27	40
MAAT-011026-DIE	3.9 3.75	4.1 4.2	4.3 4.65	21.0 17.5	27	40
MAAT-011027-DIE	6.0 6.0	6.2 6.3	6.4 6.6	21.0 17.5	27	40
MAAT-011028-DIE	10.0 9.85	10.2 10.3	10.4 10.75	21.0 17.5	27	40
MAAT-011029-DIE	15.0 15.1	15.3 15.4	15.5 15.7	21.0 17.5	27	40
MAAT-011030-DIE	20.1 19.9	20.5 20.4	21.0 20.8	21.0 17.5	27	40

Maximum Operating Conditions

Parameter	Maximum
Input Power	29 dBm
Operating Temperature	-40°C to +85°C

Absolute Maximum Ratings^{4,5}

Parameter	Absolute Maximum
Input Power	30 dBm
Storage Temperature	-65°C to +150°C

4. Exceeding any one or combination of these limits may cause permanent damage to this device.
5. MACOM does not recommend sustained operation near these survivability limits.

Handling Procedures

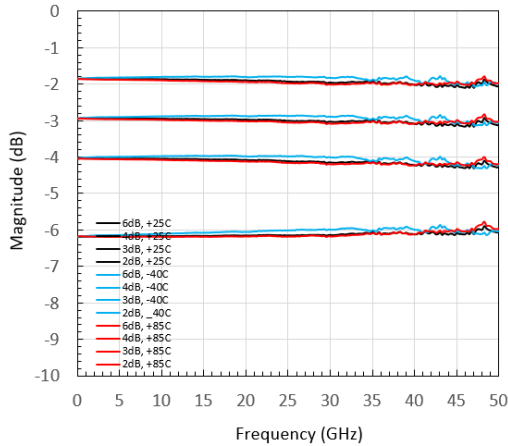
Please observe the following precautions to avoid damage:

Static Sensitivity (ESD Rating)

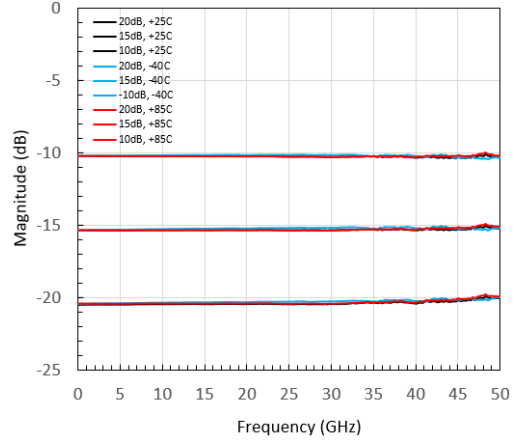
These electronic devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these devices. This device has a Class 1B HBM ESD rating

Typical Performance Curves

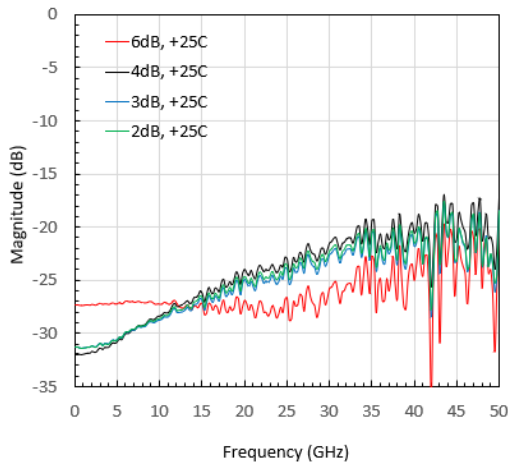
Attenuation 6 dB, 4 dB, 3 dB, and 2 dB over temp



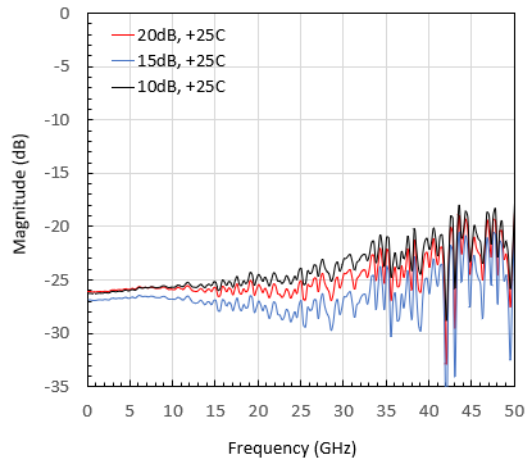
Attenuation 20 dB, 15 dB, and 10 dB over temp



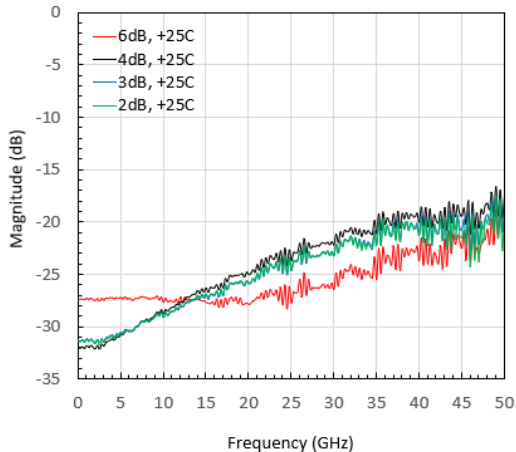
Input RL 6 dB, 4 dB, 3 dB, and 2 dB Attenuation



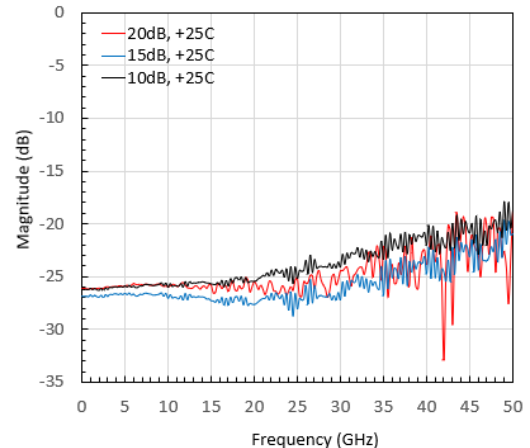
Input RL 20 dB, 15 dB, and 10 dB Attenuation



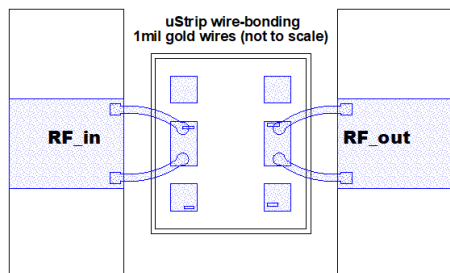
Output RL 6 dB, 4 dB, 3 dB, and 2 dB Attenuation



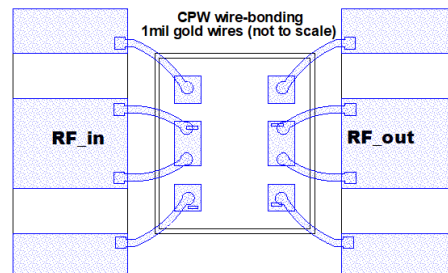
Output RL 20 dB, 15 dB, and 10 dB Attenuation



Recommended Mounting & Wire-Bonding



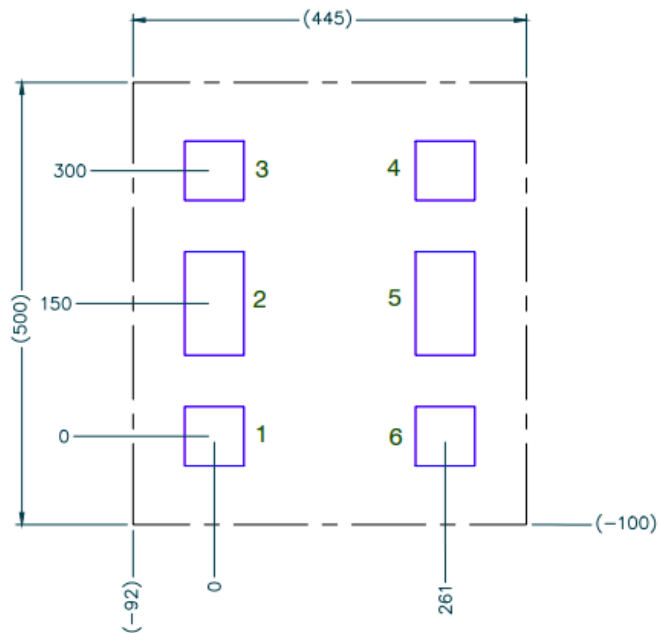
(a) Recommended Microstrip wire bonding



(b) Recommended CPW wire bonding

- The DIE should be directly attached to the RF/DC ground plane; either with solder (AuSn) or a thin application of conductive epoxy. Avoid overflows.
- 50 Ω microstrip, or 50 Ω CPW transmission lines should be brought up as close as possible to the die in order to minimize the connecting wire bonds inductances.
- A typical spacing between die and microstrip substrate should be kept between 75 - 125 μm for best RF behavior. All bonds should be kept as short as possible. Use minimum ultrasonic energy for reliable wire bonds.
- Two bond wires are recommended for the RF ports as shown above. Do not exceed a substrate height of 10 mils for any connecting RF transmission line used.

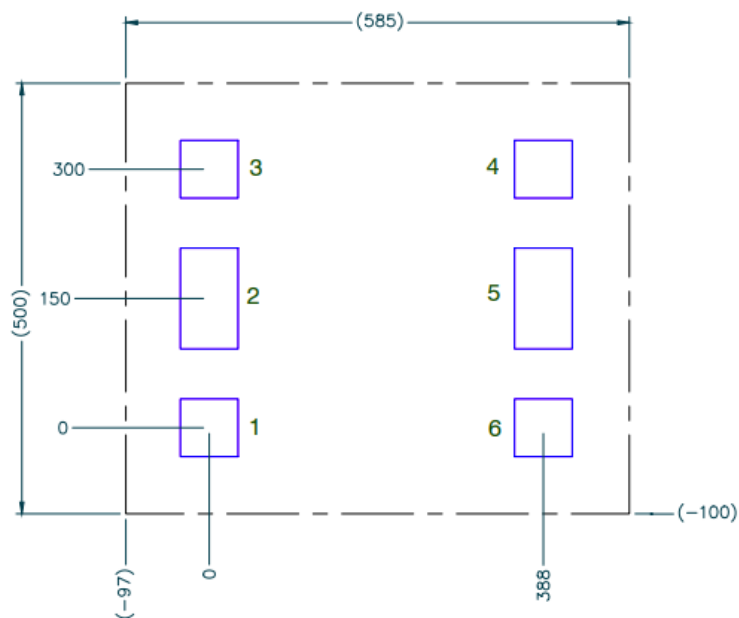
DIE Outlines



BOND PAD SIZE μm			
PAD	X(μm)	Y(μm)	PIN LABEL
1,3,4,6	67	67	GND
2	67	117	RFIN
5	67	117	RFOUT

- NOTES:
1. UNLESS OTHERWISE SPECIFIED, ALL DIMENSIONS SHOWN ARE μm WITH A TOLERANCE OF $\pm 5\mu\text{m}$.
 2. DIE THICKNESS IS $100 \pm 10\mu\text{m}$
 3. DIE SIZE REFLECTS CUT DIMENSIONS. DIE SIZE REDUCED BY $25\mu\text{m}$ EACH DIMENSION.

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